



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	10/622,346	Confirmation No.	4811
First Inventor	Sirinorakul	Filing Date	07/19/2003
Tech. Center/ Art Unit	2811	Examiner	Douglas W. Owens
Title:	Semiconductor Package Including Leadframe Roughened Using Chemical Etchant To Prevent Separation Between Leadframe And Molding Compound		
Docket No.:	NSE006 US	Customer No.:	34036

Santa Clara, California
December 2, 2005

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to Office Action dated August 3, 2005, please amend the above-identified application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Amendments to the Drawings begin on page 7 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks/Arguments begin on page 8 of this paper.

An **Appendix** including amended drawing figures is attached following page 8 of this paper.